

AMENDMENTS

IN THE CLAIMS:

- 1-2. (Canceled)
3. (Previously presented) The semiconductor device of Claim 21, wherein said second surface has a smaller area than said first surface.
4. (Canceled)
5. (Withdrawn) The semiconductor device of claim 1, wherein an outside projecting end of said leads is coated with metal.
6. (Withdrawn) The semiconductor device of Claim 5, wherein said leads are coated with metal by a plating process.
7. (Currently Amended) The semiconductor device of Claim 3, wherein there are two handg leads.
8. (Canceled)
9. (Previously presented) The semiconductor device of Claim 21, wherein the resin encapsulated body contains a tab sealed therein.
- 10-12. (Canceled)
13. (Withdrawn) A method for manufacturing a semiconductor device having a resin encapsulated body and a plurality of leads which extend into at least one surface of said resin encapsulated body, comprising the steps of:
 - interposing members between said plurality of leads to prevent resin flow between said leads;
 - performing resin molding; and

separating said interposed members from said leads.

14. (Withdrawn) The method of claim 13, further comprising the step of:
cutting off the ends of said leads.
15. (Withdrawn) The method of Claim 13, further comprising the step of:
coating said leads with a metal layer.
16. (Withdrawn) The method of Claim 15, further comprising the step of:
inserting plating holes into said plurality of leads prior to said coating step.
17. (Withdrawn) The method of Claim 13, wherein said members are push-back members.
18. (Canceled)
19. (Withdrawn) The semiconductor device of Claim 18, wherein said extending side surfaces and said extending end surface are coated with metal.
20. (Canceled)
21. (Currently amended) A semiconductor device, comprising:
a plurality of leads having a top surface, a bottom surface, two side surfaces, and two end surfaces, said leads having a square cross section shape perpendicular to the longitudinal direction of the leads;
a resin encapsulated body having a first surface, a second surface opposite said first surface, and four side surfaces through which said leads project,
each of said leads comprises a first area wherein all of said top surface, bottom surface, and two side surfaces, and one end surface are covered by said resin encapsulated body, a second area wherein said top surface is covered by said resin encapsulated body and said bottom surface and said two side surfaces are exposed from said resin

encapsulated body, and a third area wherein said top surface, bottom surface, two side surfaces, and ~~two~~ the other end surfaces are exposed from said resin encapsulated body,

further wherein said bottom surface of said second area of said leads is substantially coplanar with said second surface of said resin encapsulated body,

a lead pocket is formed between said second area of each of said leads, the depth of said lead pocket being substantially the same as the thickness of said leads along the overall length of said second area, and

said second and third areas of said leads are adapted to be mounting areas for connection to a printed circuit board.

22. (Currently amended) A semiconductor device according to Claim 37, wherein each of said ~~hang~~ leads has a top surface, a bottom surface, two side surfaces, and ~~two~~ an end surfaces, and comprises a first area wherein all of said top surface, bottom surface, and two side surfaces are covered by said resin encapsulated body, a second area wherein said top surface is covered by said resin encapsulated body and said bottom surface and said two side surfaces are exposed from said resin encapsulated body, and a third area wherein said top surface, bottom surface, two side surfaces, and ~~two~~ said end surface[s] is exposed from said resin encapsulated body.